

China Chips Star Semiconductor Co.,Ltd

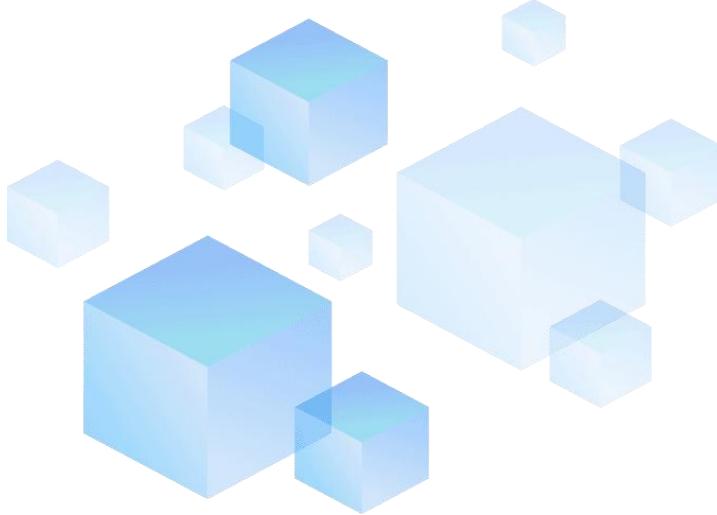
High-end embedded storage

eMMC Presentation

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01



Corporate Strength & Product Snapshot



Automotive Storage Pioneer



Company Introduction

China Chips Star Semiconductor Co., Ltd. was founded in 2022, with its headquarters in Shenzhen and branches in Hong Kong, Nanjing and Singapore. It is a national high-tech and SRDI enterprises integrating R&D, packaging, testing, sales and services. It was one of the three semiconductor enterprises in Shenzhen recognized by the Ministry of Industry and Information Technology in 2023, and also the only enterprise in China that has received strategic investment from one of the world's top four wafer manufacturers. China Chips Star Semiconductor Co., Ltd. provides a full range of storage solutions, focusing on high-end industrial grade, enterprise grade and automotive grade memory chips, and builds the professional memory chips brand- PG (Perfect Grade) .

eMMC 5.1 at a Glance: Capacity, Speed, Power, Reliability

01

Core Product

eMMC 5.1 Embedded Storage Chip offers a capacity range of 8GB-512GB, with read speeds up to 330MB/s and write speeds up to 240MB/s.

02

Low Power Consumption

Features a 30% reduction in background power consumption, making it highly efficient for various applications.

03

High Reliability

JEDEC eMMC 5.1 compliant, ensuring high reliability and compatibility with modern embedded systems.



Commercial Grade eMMC Specification

CA eMMC5.1 Specification				
型号	G2564GTLCA	G25128TLCA	G25256TLCA	G25512TLCA
NAND Flash	3DTLC NAND	3DTLC NAND	3DTLC NAND	3DTLC NAND
容量	64GB	128GB	256GB	512GB
CE	1	2	4	4
速度(读)	最高330MB/s	最高330MB/s	最高330MB/s	最高330MB/s
速度(写)	最高240MB/s	最高240MB/s	最高240MB/s	最高240MB/s
工作温度	-25°C~85°C	-25°C~85°C	-25°C~85°C	-25°C~85°C
P/E	≥3000	≥3000	≥3000	≥3000
封装规格	BGA 153	BGA 153	BGA 153	BGA 153
尺寸	11.5mmx13mmx1.0mm	11.5mmx13mmx1.0mm	11.5mmx13mmx1.2mm	11.5mmx13mmx1.2mm



Industrial Grade eMMC Specification

IA/IH eMMC5.1 Specification				
型号	G2564GTLIA	G25128TLIA	G25256TLIA	G25512TLIA
NAND Flash	3DTLC NAND	3DTLC NAND	3DTLC NAND	3DTLC NAND
容量	64GB	128GB	256GB	512GB
CE	1	2	4	4
速度(读)	最高330MB/s	最高330MB/s	最高330MB/s	最高330MB/s
速度(写)	最高240MB/s	最高240MB/s	最高240MB/s	最高240MB/s
工作温度	-40°C~85°C/-45°C ~105°C	-40°C~85°C/-45°C ~105°C	-40°C~85°C/-45°C ~105°C	-40°C~85°C/-45°C ~105°C
P/E	≥3000	≥3000	≥3000	≥3000
封装规格	BGA 153	BGA 153	BGA 153	BGA 153
尺寸	11.5mmx13mmx1.0mm	11.5mmx13mmx1.0mm	11.5mmx13mmx1.2mm	11.5mmx13mmx1.2mm



Automotive Grade eMMC Specification

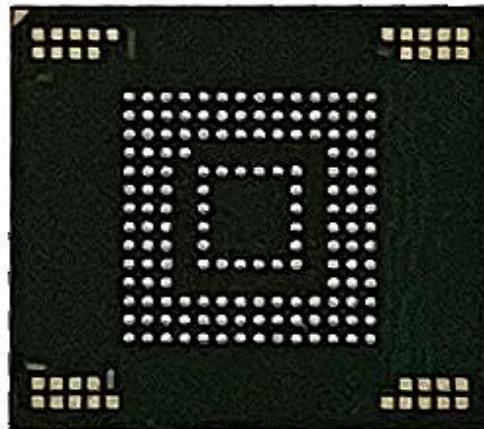
AEC eMMC5.1 Specification				
型号	G2564GTLAEC	G25128TLAEC	G25256TLAEC	G25512TLAEC
NAND Flash	3DTLC NAND	3DTLC NAND	3DTLC NAND	3DTLC NAND
容量	64GB	128GB	256GB	512GB
CE	1	2	4	4
速度(读)	最高330MB/s	最高330MB/s	最高330MB/s	最高330MB/s
速度(写)	最高240MB/s	最高240MB/s	最高240MB/s	最高240MB/s
工作温度	-45°C~105°C	-45°C~105°C	-45°C~105°C	-45°C~105°C
P/E	≥5000	≥5000	≥5000	≥5000
封装规格	BGA 153	BGA 153	BGA 153	BGA 153
尺寸	11.5mmx13mmx1.0mm	11.5mmx13mmx1.0mm	11.5mmx13mmx1.2mm	11.5mmx13mmx1.2mm

02

Core Technology Deep Dive



KIOXIA 9T25 3D TLC: Density, Endurance, Wide-Temp



01

Advanced 3D Architecture

KIOXIA BiCS FLASH™ 3D TLC NAND features an advanced 112-layer vertical stacking technology, significantly increasing storage density.

02

Enhanced Endurance

Delivers up to 10,000 P/E cycles in TLC mode, providing a theoretical service life of 8 years in industrial scenarios.

03

Extreme Environment Adaptability

Data retention of 10 years within an industrial temperature range of -40°C to 85°C, maintaining 98% performance at -40°C.

SMI Controller: LDPC & Power-Fail 2.0

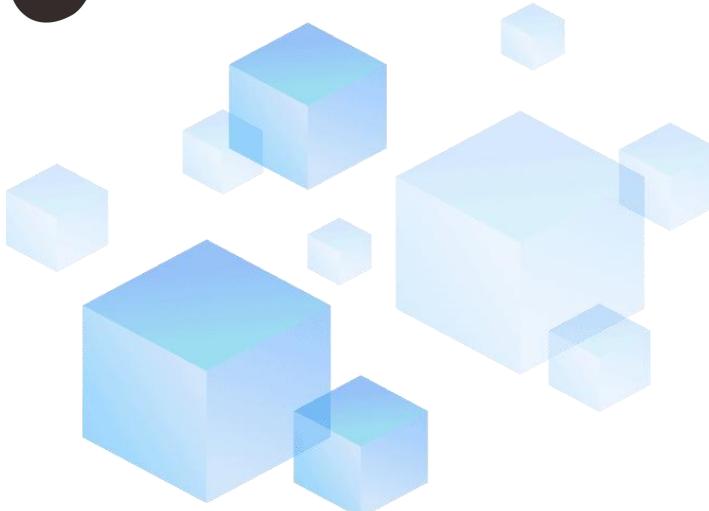
LDPC Error Correction

To address the inherent reliability challenges of advanced NAND flash memory (like TLC and QLC), SMI employs a powerful 4K LDPC (Low-Density Parity-Check) engine. This technology offers significantly stronger error correction capabilities compared to older 1K or 2K LDPC schemes, which is crucial for maintaining data integrity



Intelligent Power Failure Protection 2.0

SMI has optimized its LDPC design to balance performance and efficiency. Despite the increased complexity of the 4K LDPC, their implementation keeps the increase in power consumption and silicon area to around 20%. This efficient design is important for embedded storage solutions where power and space are often constrained.



03.



Patent Qualification





■ ISO9001



■ 30 invention patents 10 patents in application



■ 25 software copyrights/ utility model patents
More than 100 intellectual property rights



■ More than 10 products have passed CE/RoHS certification



■ TUV | AATF 16949



■ Alibaba International Station Gold Medal Supplier

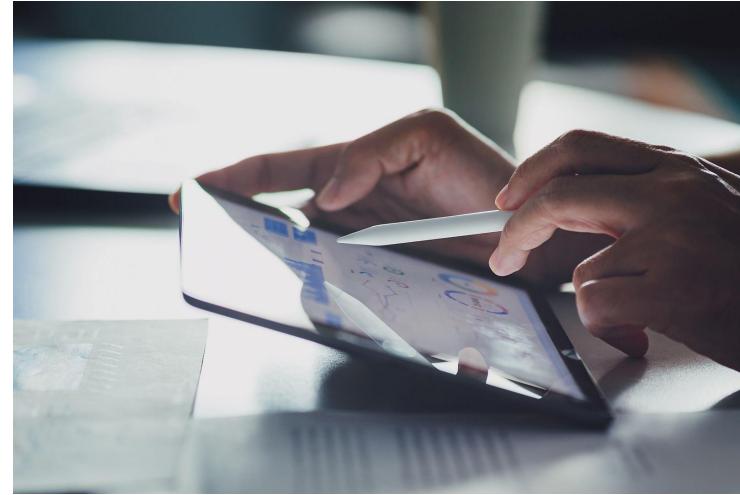


■ Specialized, Refined, Characteristic and Innovative SMEs
■ High-Tech
■ Enterprises Innovative SMEs
■ Technology SMEs

Scenario Matrix: -45 °C ADAS to 85 °C PLC

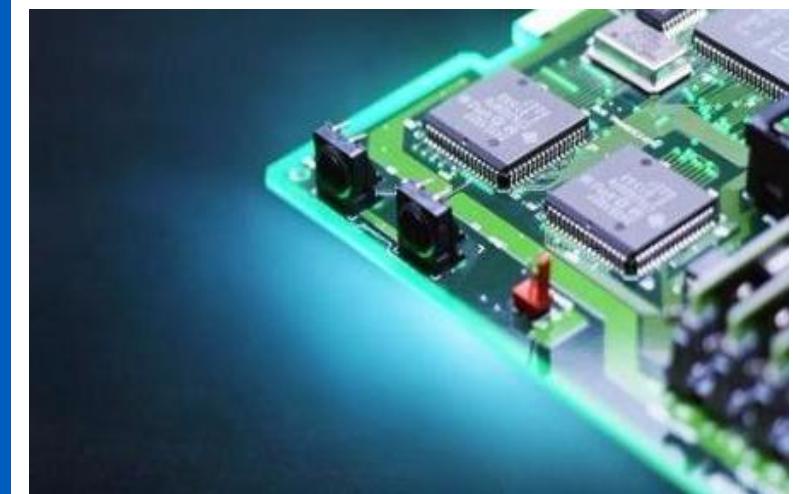
Automotive Electronics

Ideal for automotive applications such as IVI systems, ADAS, and automotive electronics, supporting temperatures down to -45°C.



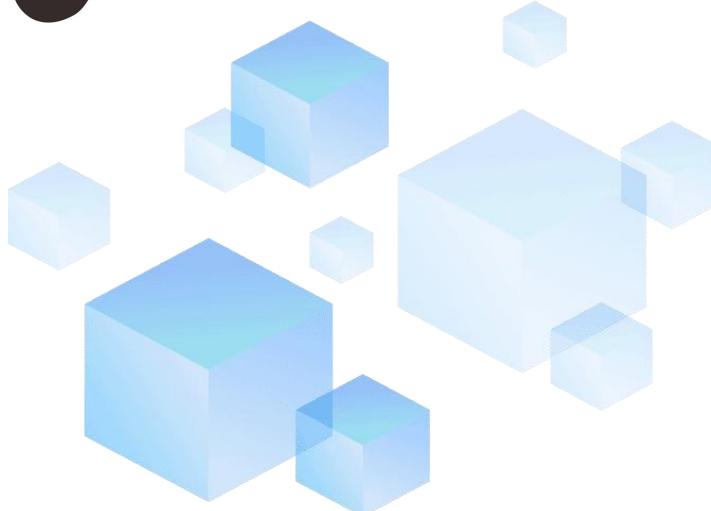
Industrial Automation

Suitable for industrial controllers and automated equipment, withstanding temperatures up to 85°C.



Consumer Electronics & IoT

Provides high-performance, low-power storage solutions for smartphones, tablets, smart TVs, and IoT devices.



04.



Market Edge & Supply Security





Hexagon Warrior: Industrial, Automotive, Consumer

Industrial

Offers 10,000 P/E cycles and a wide temperature range of -40°C to 105°C, making it highly reliable for industrial applications.

Automotive

Compliant with TUV IATF16949 and ISO9001, ensuring safety and reliability in automotive electronics.

Consumer

Delivers 290MB/s read speed, 130µA standby power consumption, and a 1-year warranty, ideal for consumer electronics.



Supply-Security & Cost-Optimization Engine



Technology Integration

Combines KIOXIA wafers with SMI controllers to deliver high-performance and reliable storage solutions.



Cost Advantage

Achieves an 18% reduction in BOM costs in automotive projects, providing significant cost savings.



Independent R&D

Features complete supply chain control through independent R&D, ensuring supply security and cost optimization.



Competitive Advantages

Stable support from the upstream, midstream, and downstream industrial chain



Competitive Advantages



High quality customers

Communication terminal

HONOR 荣耀

TRANSSION
传音控股

ZTE 中兴

ajhua 大华股份
TECHNOLOGY

Mobile platform

紫光展锐
UNISOC

MEDIATEK
聯發科技

Qualcomm
高通

Multimedia and IoT platforms

Rockchip
瑞芯微电子

Allwinner
全志科技

@mlogic
晶晨半导体

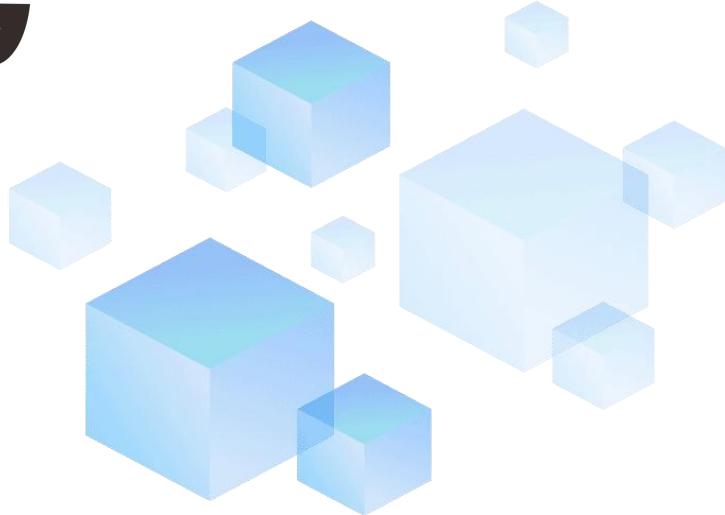
Laptop and server platform

HUAWEI

兆芯

HYGON
中科海光

intel
AMD



05.



Value Recap & Roadmap



Millisecond Response, Decade Lifespan: Store Here



Value Summary

Chia Chips Star eMMC 5.1 delivers nanometer-level precision, millisecond-level response, and decade-level data longevity, making it the ideal choice for modern embedded storage.

Industry 4.0

Perfectly suited for Industry 4.0 applications, providing reliable and high-performance storage solutions.

Smart Cars & 5G IoT

Empowers smart cars and 5G IoT devices with its advanced technology and long-lasting data retention capabilities.



PG SMI-eMMC~UFS Roadmap (2024~2026)

Model	2025 Year				2026 Year				备注
	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	
eMMC5.1			SMI2732+BiCS5 (64GB~128GB~256GB)		SMI2732+BiCS5 (工规) (64GB~128GB~256GB)			SMI2732+BiCS5 (车规) (64GB~128GB~256GB)	
					SMI2732+BiCS8 (128GB~256GB~512GB)		SMI2732+BiCS4 (32GB)		
UFS				UFS3.1 BiCS8TLC (256GB~512G~1TB)		UFS3.1 BiCS8 QLC (256GB~512G~1TB)		UFS4.1 BiCS8 TLC (256GB~512G~1TB)	

规格型号说明：

SMI: 慧荣科技股份有限公司 英文名称: Silicon Motion

BiCS 4/5/8: KIOXIA Group



PG SA-eMMC5.1 Roadmap (2024~2026)

Model	Roadmap	2024 Year	2025 Year				2026 Year				备注
			Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	
eMMC5.1					SA3636+BiCS5 (64GB~128GB~256GB)						

规格型号说明：

SA:深圳衡宇芯片科技有限公司 英文名称: StorArt

BiCS 5/8: KIOXIA Group



THANK YOU FOR WATCHING

Presenter:Lily

Time:2025/11/06

